

AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application:

LISTING OF CLAIMS:

1-9. (canceled)

10. (currently amended) A jig for calcining an electronic component, comprising:

a substrate, and

a zirconia layer prepared by bonding coarse zirconia having an average particle size from 30 to 500 μ m and fine zirconia having an average particle size from 0.1 to 10 μ m by means of a partially fused-bonding agent, and coated on the substrate, characterized in that the partially fused-bonding agent is ~~aluminum oxide~~ or alumina-magnesia-based spinel composite oxide.

11. (cancelled)

12. (currently amended) A jig for calcining an electronic component, comprising:

a substrate, and

a zirconia layer prepared by bonding coarse zirconia having an average particle size from 30 to 500 μ m and fine zirconia having an average particle size from 0.1 to 10 μ m by means of a partially fused-bonding agent, and coated on the

substrate, characterized in that the partially fused-bonding agent is a mixture of two or more metal oxides selected from the group consisting of rare earth metal oxides, transition metal oxides and alkaline earth metal oxides.

13. (currently amended) A jig for calcining an electronic component, comprising:

a substrate, and

a zirconia layer prepared by bonding coarse zirconia having an average particle size from 30 to 500 μ m and fine zirconia having an average particle size from 0.1 to 10 μ m by means of a partially fused-bonding agent, and coated on the substrate, characterized in that the partially fused-bonding agent is a mixture of one or more metal oxides selected from the group consisting of rare earth metal oxides, transition metal oxides and alkaline earth metal oxides, and alumina-magnesia-based spinel-type composite oxide.

14. (previously presented) The jig for calcining the electronic component as defined in claim 10, wherein an intermediate layer is formed between the substrate and the zirconia layer.

15. (original) The jig for calcining the electronic component as defined in claim 14, wherein the intermediate layer contains alumina, alumina-zirconia or alumina-magnesia-based spinel.

16. (previously presented) The jig for calcining the electronic component as defined in claim 10, wherein the substrate is made of baked-mud or porcelain.

17. (previously presented) The jig for calcining the electronic component as defined in claim 10, wherein a weight ratio between the coarse zirconia and the fine zirconia plus the partially fused-bonding agent is between 75:25 and 25:75.

18. (previously presented) The jig for calcining the electronic component as defined in claim 10, wherein a weight ratio of the partially fused-bonding agent toward the coarse zirconia plus the fine zirconia plus the partially fused-bonding agent is 3 % in weight or more and below 25 % in weight.

19-27. (canceled)